

# Ryan R Gusley

## List of Publications by Year in descending order

Source: <https://exaly.com/author-pdf/964345/publications.pdf>

Version: 2024-02-01

7

papers

75

citations

1684188  
5

h-index

1720034  
7

g-index

8

all docs

8

docs citations

8

times ranked

83

citing authors

#	ARTICLE	IF	CITATIONS
1	Electrodeposition of Ru onto Ru and Au Seed Layers from Solutions of Ruthenium Nitrosyl Sulfate and Ruthenium Chloride. <i>Journal of the Electrochemical Society</i> , 2021, 168, 052504.	2.9	3
2	Electrodeposition of Cu(111) onto a Ru(0001) seed layer for epitaxial Cu interconnects. <i>Journal of Applied Physics</i> , 2021, 130, 135301.	2.5	1
3	Epitaxial metals for interconnects beyond Cu. <i>Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films</i> , 2020, 38, .	2.1	29
4	Influence of the Seed Layer and Electrolyte on the Epitaxial Electrodeposition of Co(0001) for the Fabrication of Single Crystal Interconnects. <i>Journal of the Electrochemical Society</i> , 2020, 167, 162503.	2.9	7
5	Electrochemistry-enabled atomic layer deposition of copper: Investigation of the deposit growth rate and roughness. <i>Journal of Vacuum Science and Technology A: Vacuum, Surfaces and Films</i> , 2019, 37, 020901.	2.1	6
6	Electrodeposition of Epitaxial Co on Ru(0001)/Al <sub>2</sub> O <sub>3</sub> (0001). <i>Journal of the Electrochemical Society</i> , 2019, 166, D875-D881.	2.9	8
7	Electrochemical Atomic Layer Deposition of Copper: A Lead-Free Process Mediated by Surface-Limited Redox Replacement of Underpotentially Deposited Zinc. <i>Journal of the Electrochemical Society</i> , 2016, 163, D3008-D3013.	2.9	21